

Potential of Thin Film Detectors

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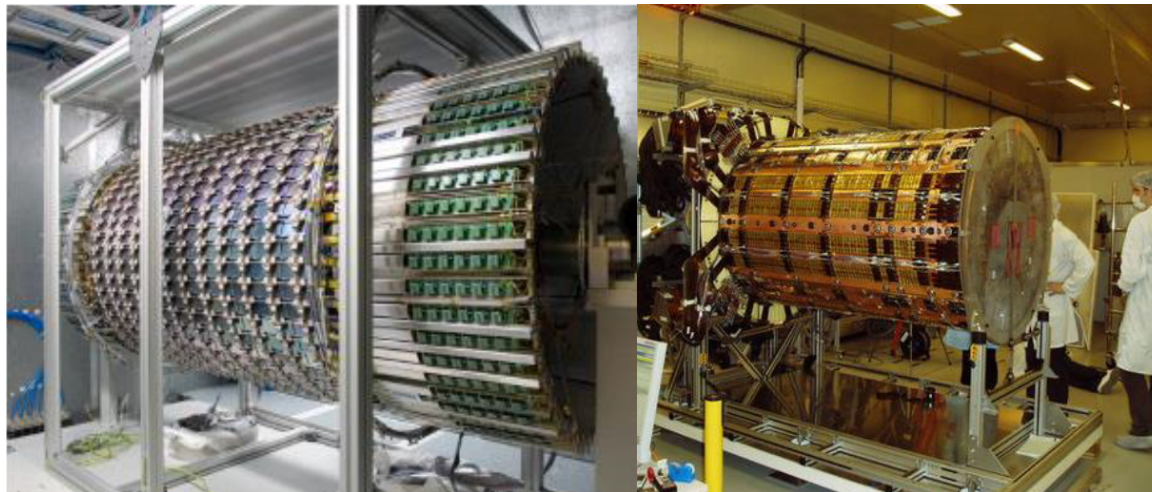
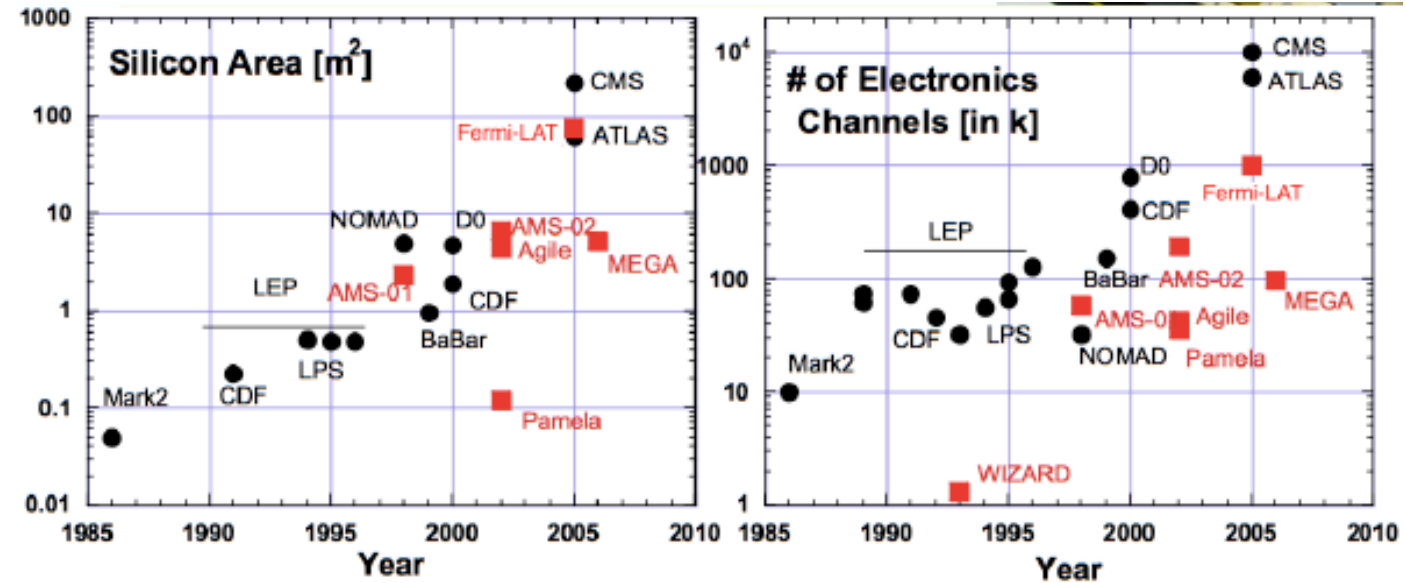
Motivation

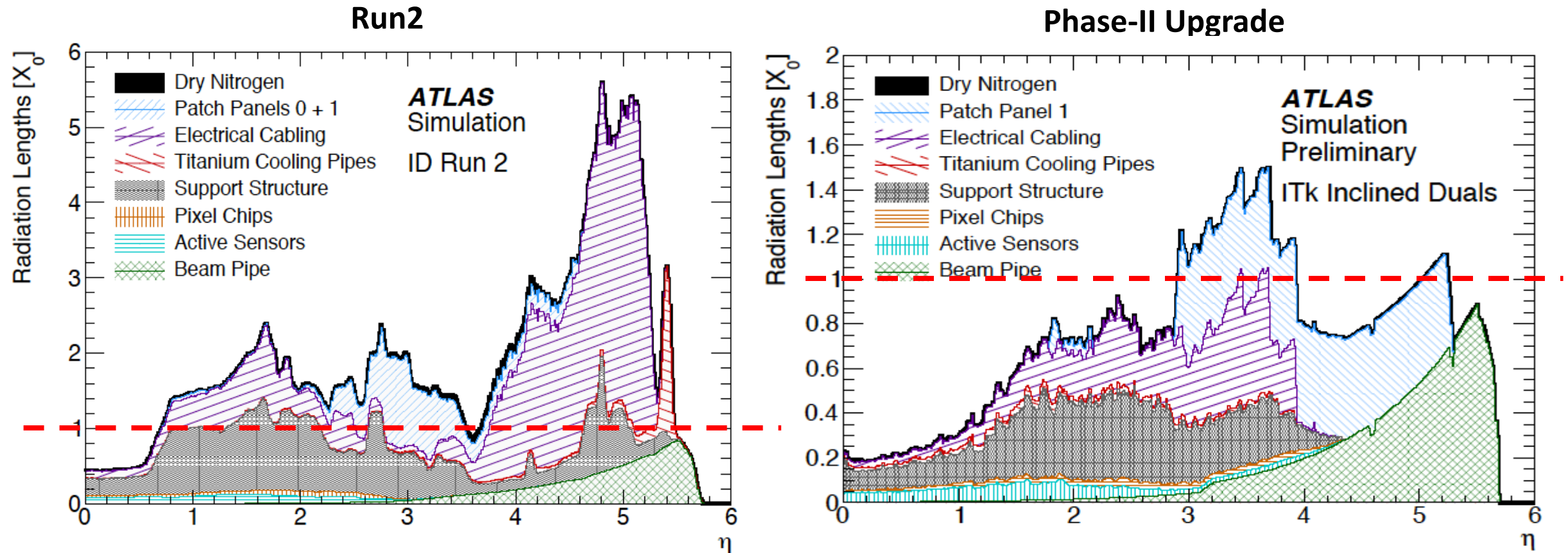
Silicon detectors are a cornerstone of High Energy Physics

Larger fractions of detectors are made with silicon

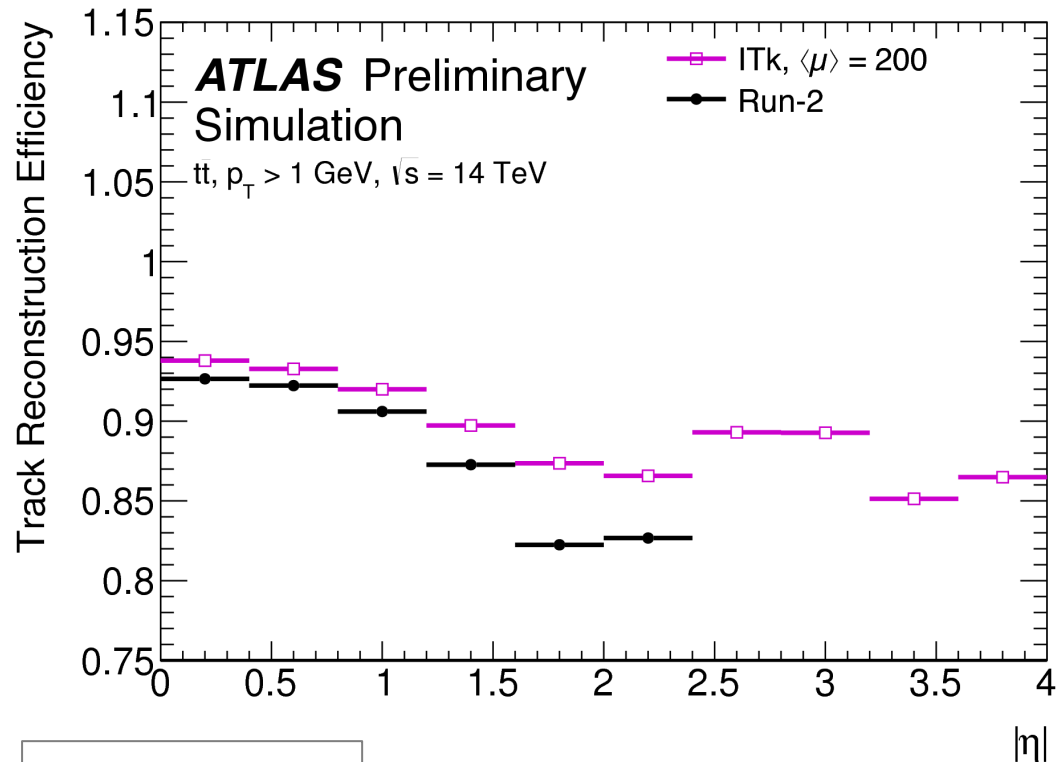
- More layers for precise tracking
- Limiting factor is often the cost
- Shift toward high precision silicon calorimeters

Can we come up with an alternative that might have an advantage?

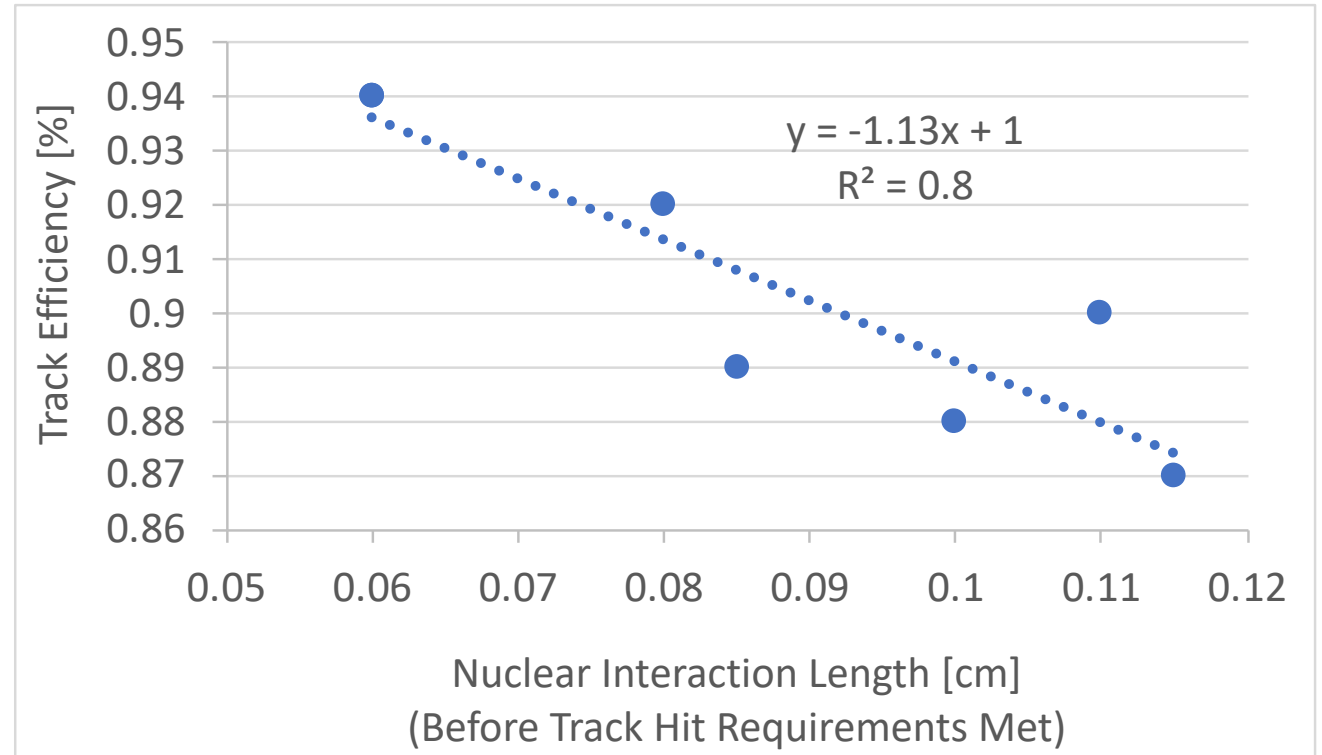




- Tremendous progress since the original ATLAS
- Target support structures & services
- Continue this trend



ATLAS-TDR-030



- A single silicon sensor has very high intrinsic tracking efficiency $> 99\%$
- A detector system, however, is limited by the dead material
- Overall tracking efficiency can be optimized by reducing dead material

- Low Mass
- Low power
- High position resolution
- Fast timing resolution
- Monolithic
- Radiation Tolerance
- Energy resolution
- Energy range: signal/noise
 - Low electron energies
- Low cost
- Reduce services
- Reduce cooling needs
- All-in-one?
 - Fewer 'sub-systems'
 - Reduce cost
 - Optimize resources
- Faster development cycle

How many features can we combine into one detector technology?

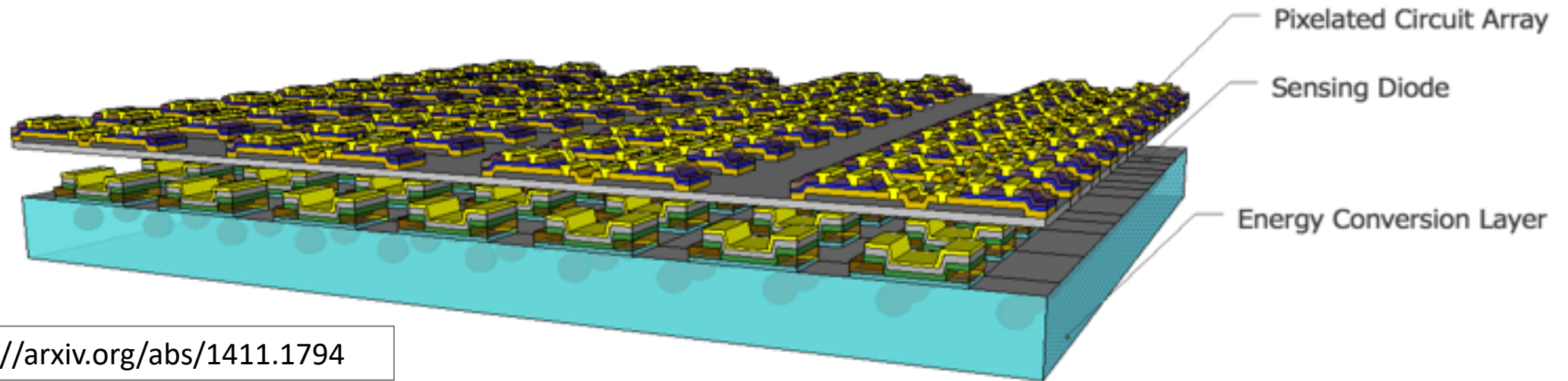
Thin Film Detectors

Thin Films: thin layers of materials ranging from nm to μm

- Current popular applications
 - solar cells
 - LCD screens
- Thin Films for Particle Detectors:
 - Thin Film Diodes + Thin Film Transistors

Potential:

- Large area 'printing'
- Low mass
- Low cost
- Pixelated
- Integrated/monolithic design



<https://arxiv.org/abs/1411.1794>

Thin Film Detectors: Materials

- Many potential materials with promising properties
- Catalogue potential material candidates
 - Fabrication techniques
 - Key performance parameters
 - Challenges related to individual materials

Material	Z	ρ (g/cm ³)	$\frac{-dE}{dx}$ [MeV/(g/cm ²)]	MIP in 10 μ m (keV)	E_i (eV)	$< N_{e-h \text{ pairs}} >$ in 10 μ m
Diamond	6	3.51	1.78	6.25	13	0.5k
Si	14	2.329	1.664	3.9	3.62	1.1k
CdS	32	4.8	4.0*	19.08	6.49*	2.9k
PbS	49	7.6	6.2*	46.8	1.98*	23.6k
ZnO	19	5.6	4.4*	24.8	8.25*	3.0k
GaAs	32	5.32	1.4	7.45	4.2	1.8k
InP	32	4.97	4.0*	20.5	4.2	4.8k
HgI	66.5	6.4	5.6*	35.8	4.3	8.3k
InSb	50	5.78	4.9*	28.1	1.57*	17.9k
InAs	41	5.67	4.7*	26.8	1.94*	13.8k
HgTe	66	8.1	6.7*	54.7		
CdZnTe	43.3	6	5.0*	29.8	4.7	6.3k
IGZO	29.5	6			7.58*	

*calculated

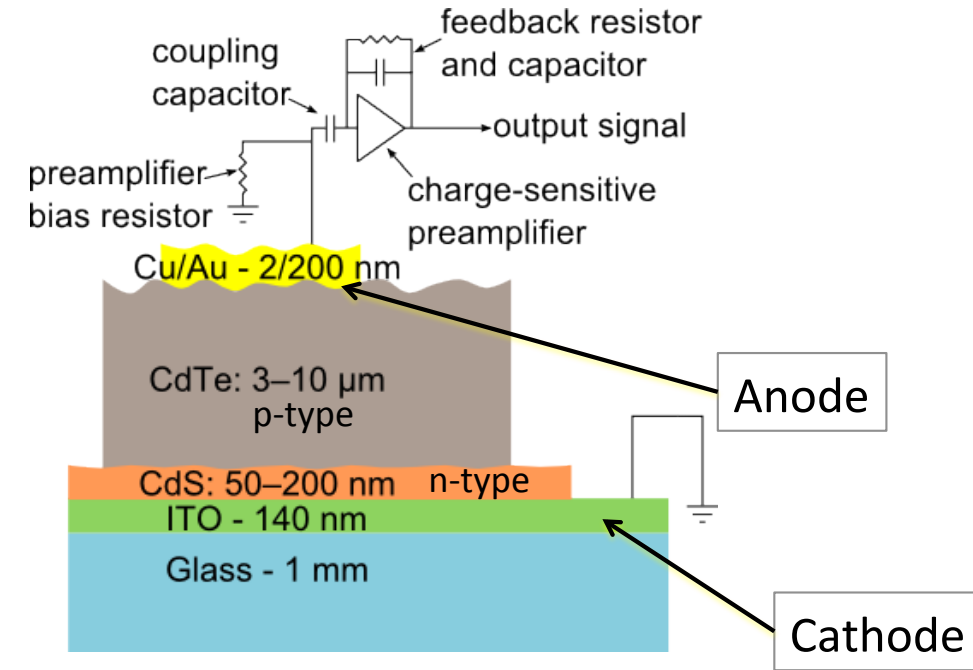
Material	μ_e ($\frac{cm^2}{V.s}$)	μ_h ($\frac{cm^2}{V.s}$)
Diamond	1800	1200
Si	1350	480
CdTe	1050	100
CdS	340	50
PbS	600	700
ZnO	130	
IGZO	15	0.1
GaAs	8000	400
InP	4600	150
HgI	100	4
InSb	78000	750
InAs	33000	460
HgTe	22000	100
CdZnTe	1350	120

<https://arxiv.org/abs/1411.1794>

Thin Film Detectors: Fabrication

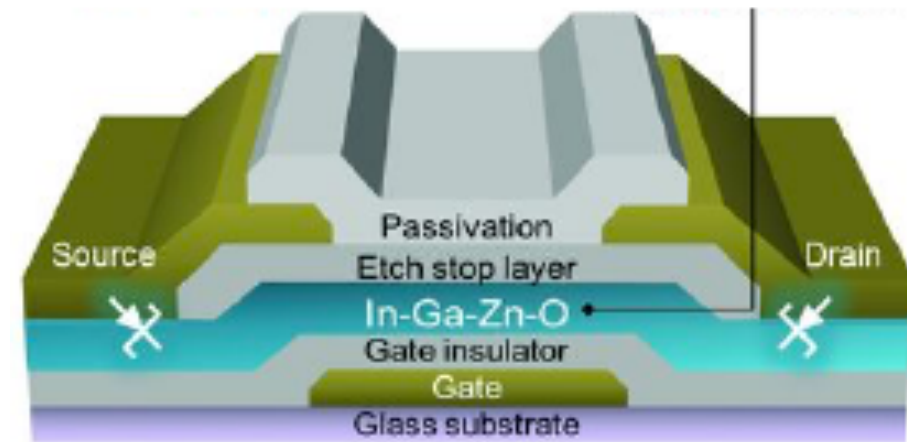
Thin Film (TF) Fabrication

- Films are grown in thin layers on a substrate with high precision
- Compare to traditional silicon that relies on growing a large crystal and then drilling, etching, etc.
- Thin Films can be fabricated using
 - chemical bath deposition
 - close-space sublimation
 - Atomic layer deposition
- TF's can be grown at least 200 μm thick (not standard)
- Certain types of Thin Film fabrication are much less expensive
 - < \$10 per m^2 for a 2.5 μm thick CdTe film
- TF can be deposited on flexible substrates such as organic polymers and plastics



- Services is a large part of the dead material
- Low power electronics can help
- Thin Film Transistors is a large area of nanoscience development
- Explore options for HEP
 - Example:
 - High gains > 400
 - Low power < 1 nW
 - Potential integration in thin film detector

Thin Film Transistors (TFTs): Ultralow Power



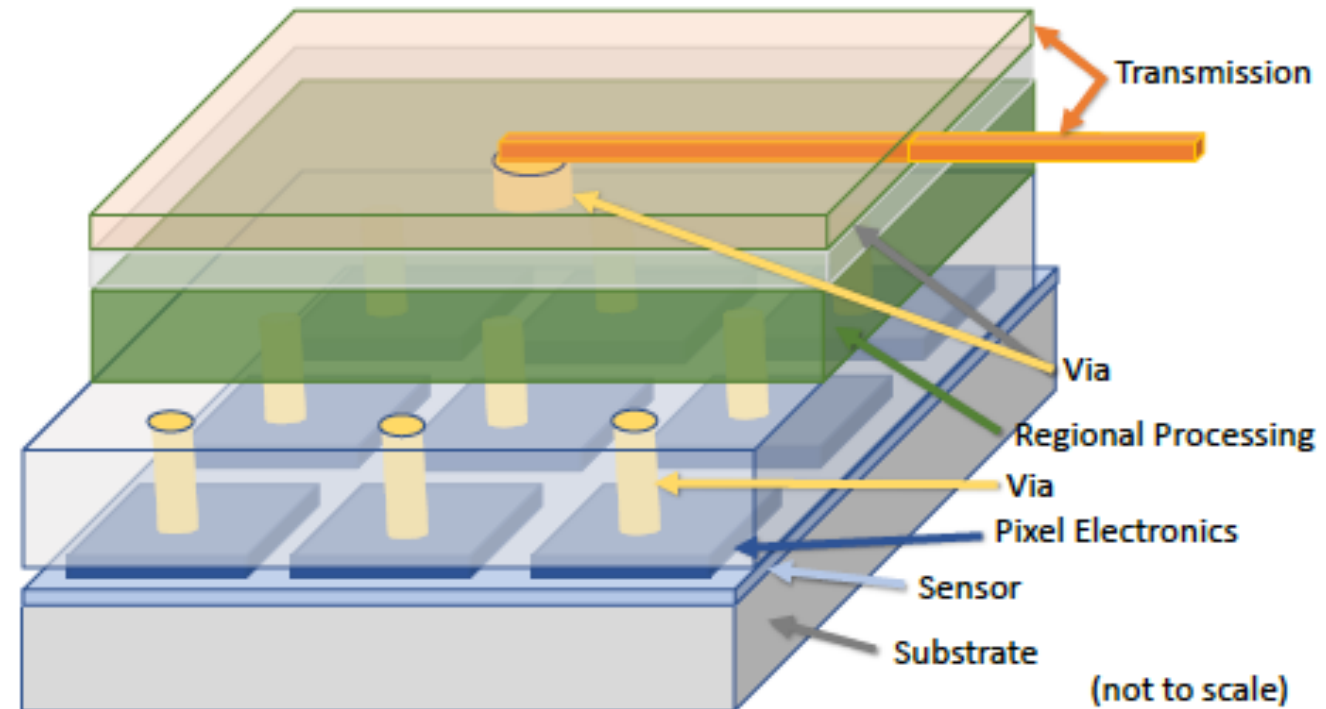
Sungsik Lee and Arokia Nathan. Subthreshold Schottky-barrier thin-film transistors with ultralow power and high intrinsic gain. *Science*, 354(6310):302–304, 2016.

Thin Film Detectors

- Combine thin film layers into a complete detector
- Consider thin film deposition techniques
 - Potential to be large area low cost like LCD screens
- Options for many different semiconductor materials
- Potential for monolithic integration of sensor + electronics
- Minimize services radiation length
- $< 1\% X/X_0$

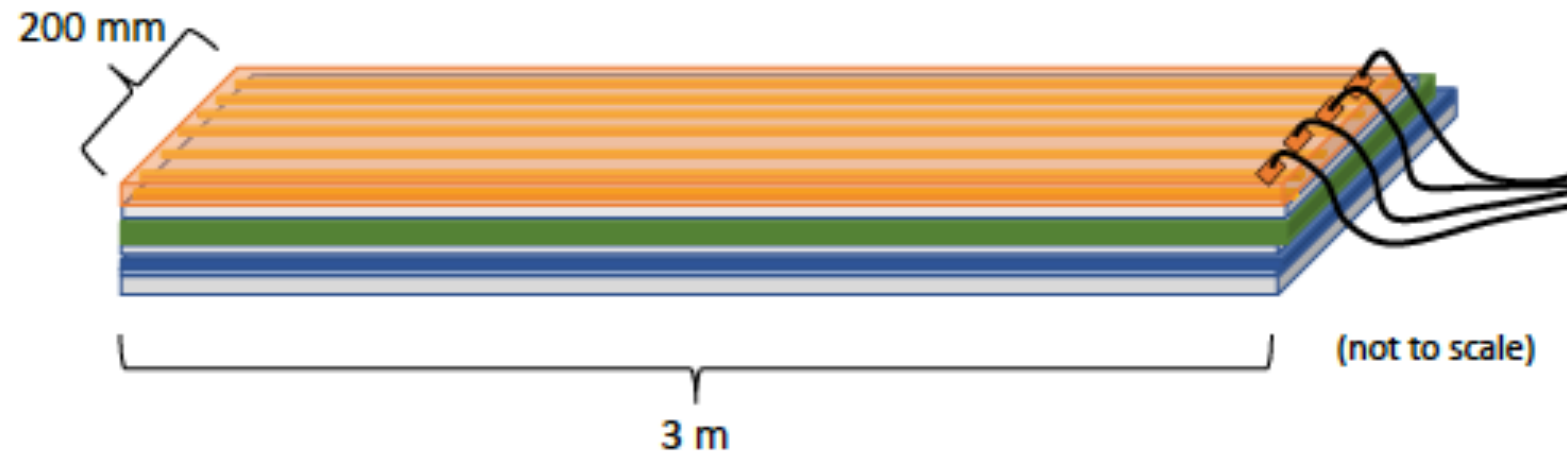
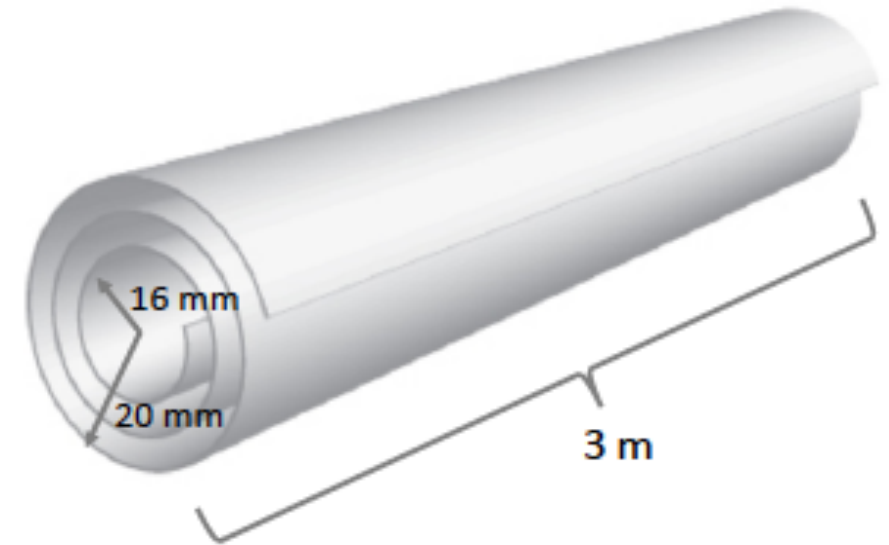
Layer	Material	thickness [μm]	X_0 [cm]	X/X_0	λ_0 [cm]	λ/λ_0
Substrate	PET	250	29	0.088%	60.6	0.041%
Sensor	InSb	10	15	0.0065%	46.8	0.0021%
Electronics	InGaZnO	200	10	0.20%	45.0	0.044%
1st Via	Cu/dielectric	100	29	0.035%	60.2	0.017%
Electronics	InGaZnO	200	10	0.20%	45.0	0.044%
2nd Via	Cu/dielectric	100	25	0.04%	51.2	0.020%
Transmission	Cu/dielectric	250	20	0.13%	45.4	0.055%
Total				0.70%		0.22%

Thin Film Detector Layers:



Large area design possibilities:

- Fabricate on a single flexible substrate
- Creative detector geometries like spiral cylinder roll
- Simplify detector construction process
- Move toward a single active detector system



Key Challenges:

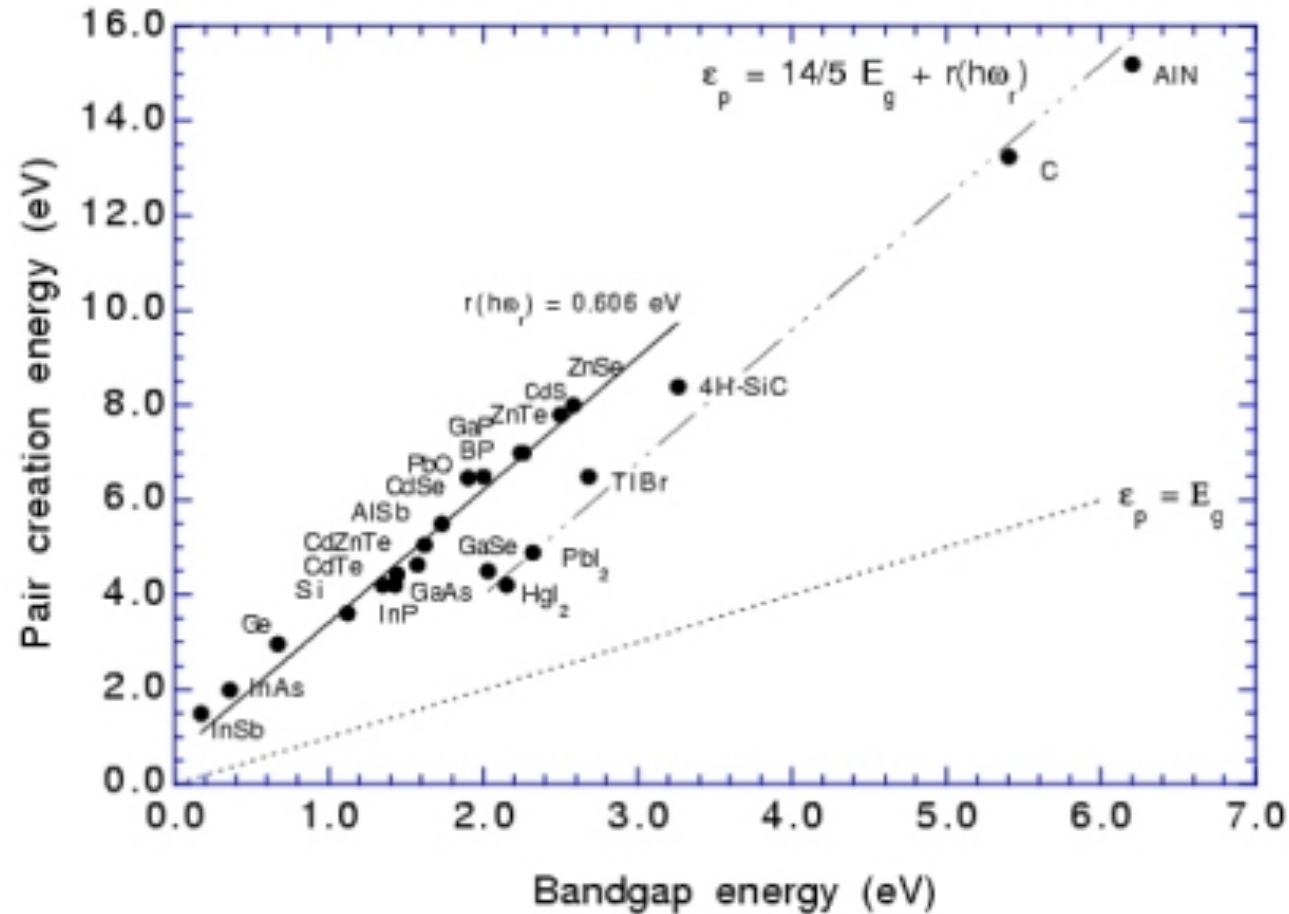
- Sensor performance
 - Want to match silicon sensor performance
- Transistor designs
 - Compatible fabrication processes on top of sensor
 - Transistor footprint
- Vertical integration
 - How to reliably stack layers
 - Over large areas
- Transmission signal integrity over long distances
- Radiation damage
- Process industrialization

Potential of a Thin Film Detector design:

- Material level understanding to design and optimize a given detector design for a specific application
 - Tracking efficiency
 - Timing resolution
 - Energy resolution
 - Occupancy
 - Radiation damage
 - Etc.
- Simplify fabrication techniques to follow industrial standards
 - Large area
 - 'Printable' designs
 - monolithic
 - Low cost
 - Fast turn-over cycle
- A lot of unknowns to realize the full potential → Long-term blue-sky R&D
- Interesting path to see where it leads

Backup

Use the bandgap energy, E_g , to estimate E_i : $E_i \propto E_g$

$$E_i \approx 2.0877 \cdot E_g + 1.2122$$


Material	E_g (eV)	E_i (eV)
Ge	0.67	2.96
Si	1.11	3.62
CdTe	1.4	4.43
GaAs	1.43	4.2
diamond	5.5	13

Design Goals

Meet current tracking performance of a typical tracking detector such as ATLAS

- Charge yield 1,000 – 10,000 electrons
- Energy resolution 5-10%
- Position resolution $\sim 45 \mu\text{m}$
- Timing resolution 25 ns
- Signal/Noise ~ 20

Other applications: ILC

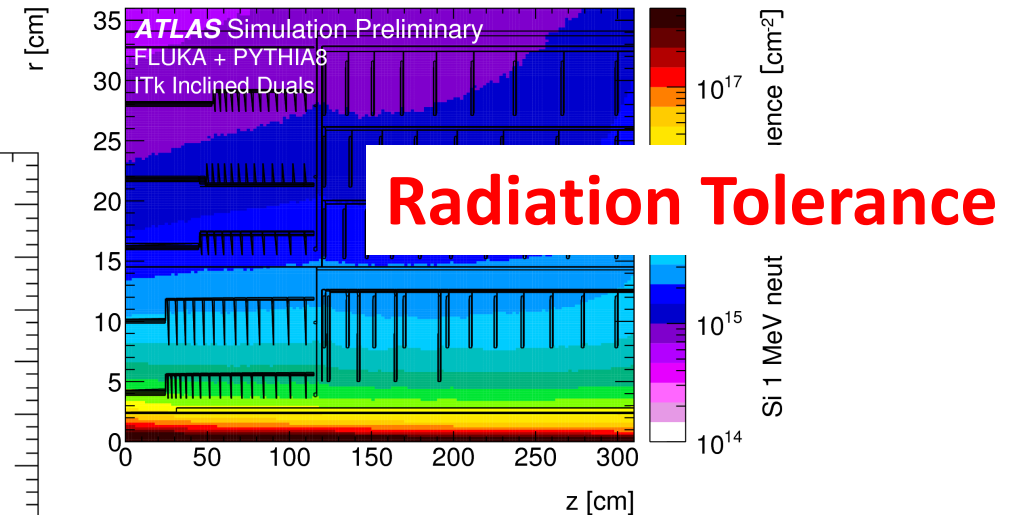
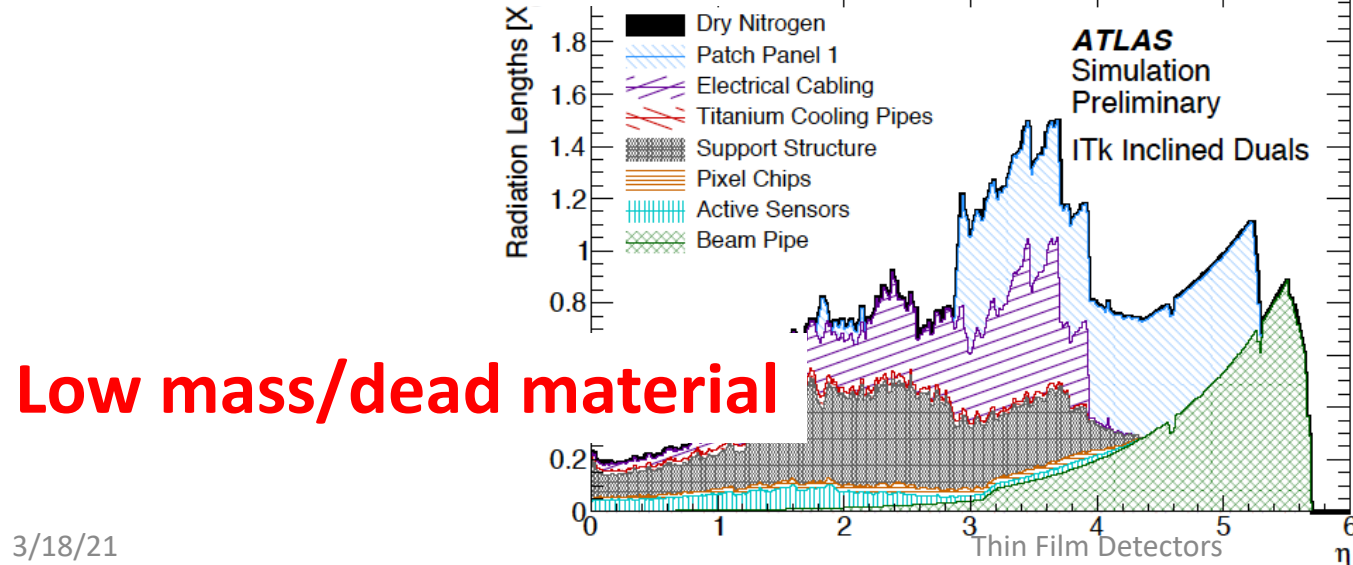
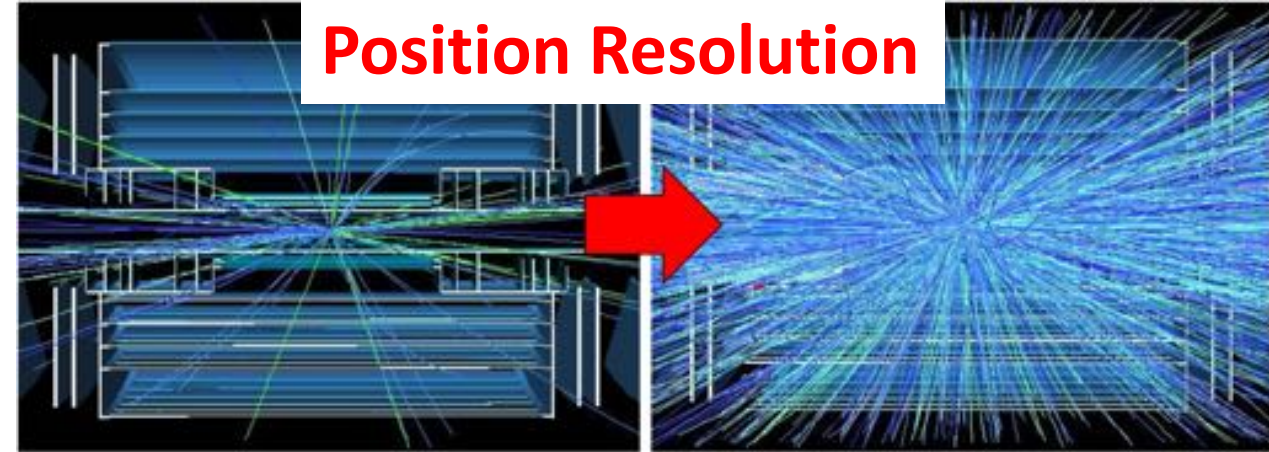
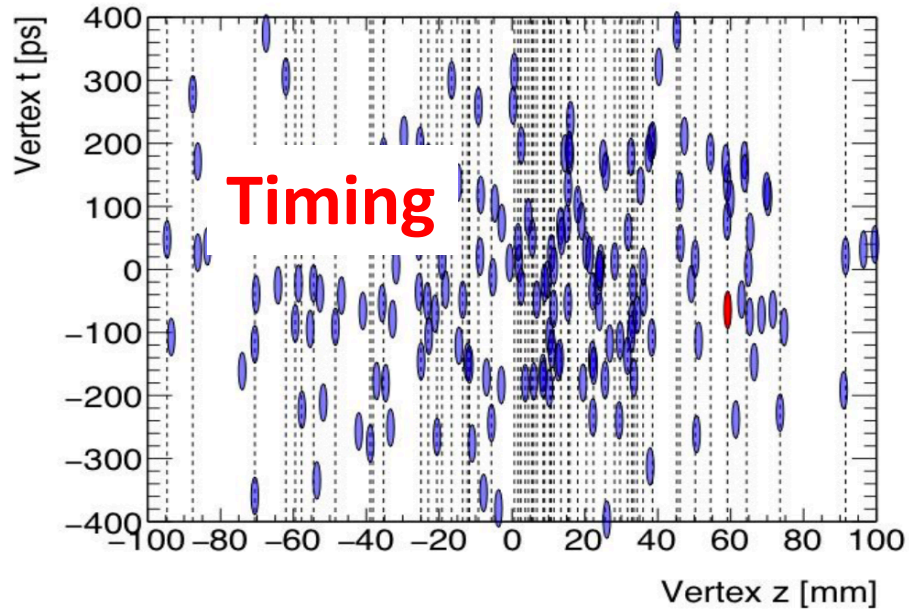
- Timing resolution 5 ns
- Tracking precision $3 \mu\text{m}$
- $0.1\% X_0$
- $\sim 10^{14} \text{ 1 MeV } N_{\text{eq}}/\text{cm}^2$



Flexible layers “printed” in large sheets

➔ Possibility for unique geometries with less dead space

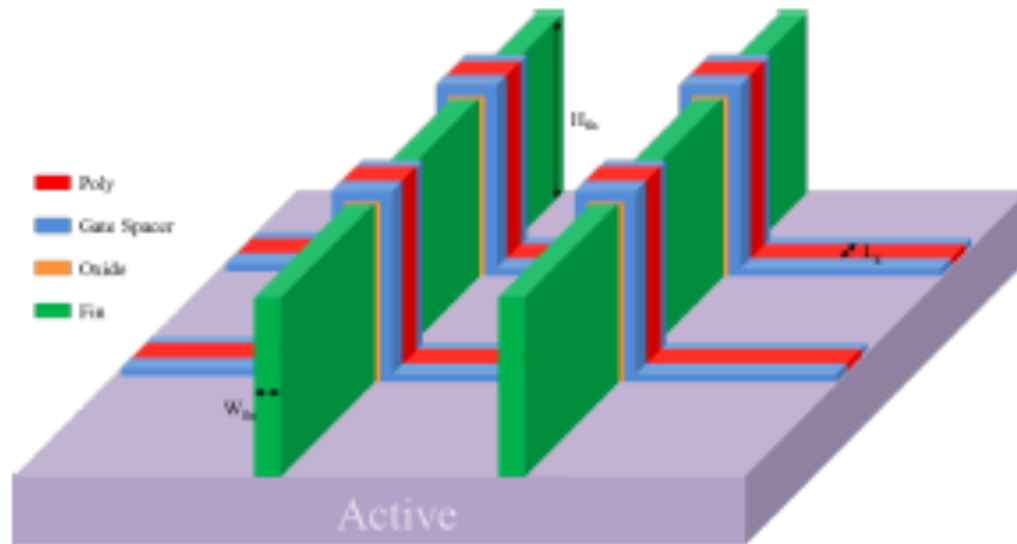
Challenges



...Typical of large accelerator experiments

- FinFETs
 - ~30% less power than CMOS
 - Faster switching times
 - Energy harvesting interfaces
 - 'self-powering'
 - Can we take advantage?

FinFETs

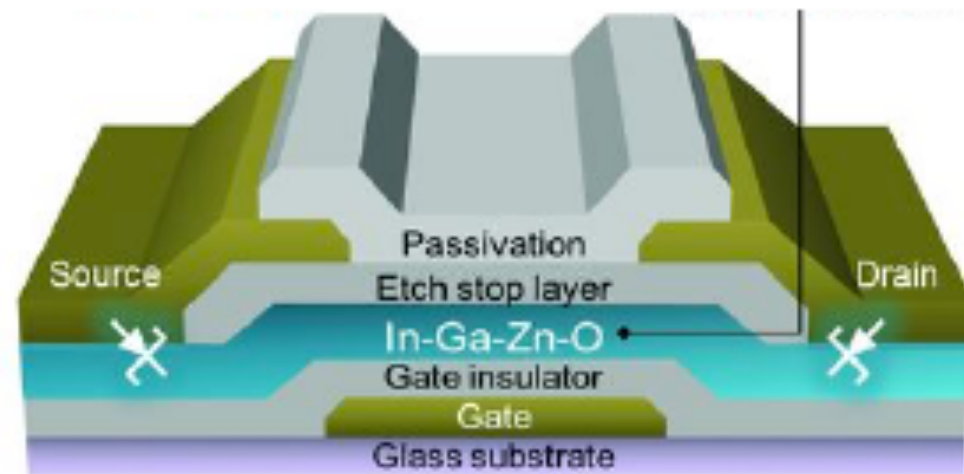


Katrine Lundager, Behzad Zeinali, Mohammad Tohidi, Jens K. Madsen, and Farshad Moradi. Low Power Design for Future Wearable and Implantable Devices. *J. Low Power Electron. Appl.*, 6(64):20, 2016.

3/18/21

- TFTs
 - High gains > 400
 - Low power < 1 nW
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Thin Film Transistors (TFTs)



Sungsik Lee and Arokia Nathan. Subthreshold Schottky-barrier thin-film transistors with ultralow power and high intrinsic gain. *Science*, 354(6310):302-304, 2016.